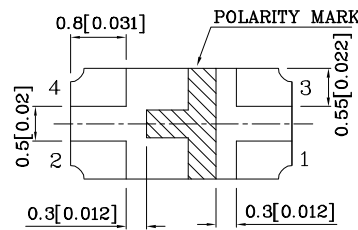
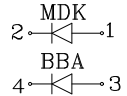
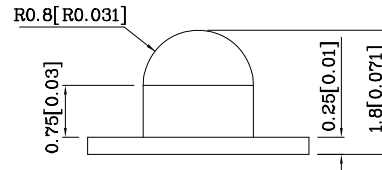
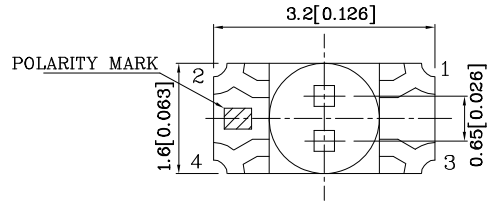


PRELIMINARY SPEC

Features

- 3.2mmx1.6mm SMT LED, 1.8mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.



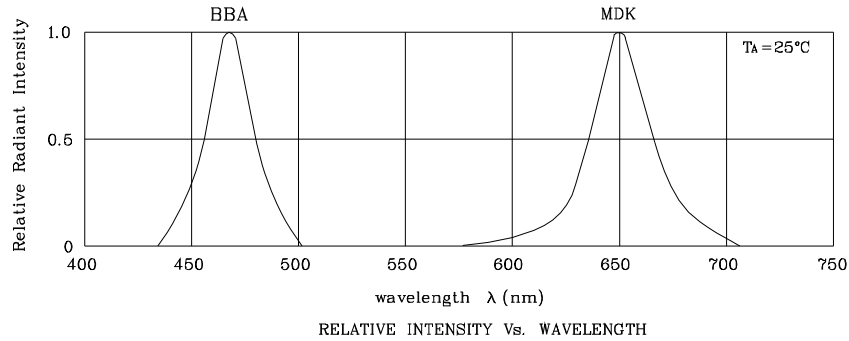
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ " unless otherwise noted.
3. Specifications are subject to change without notice.

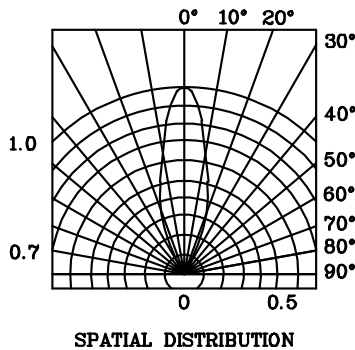
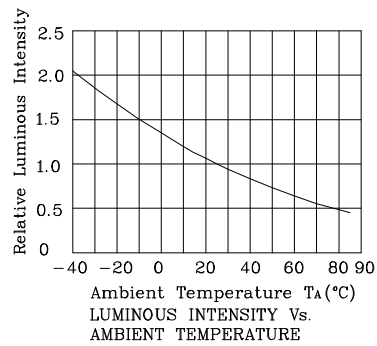
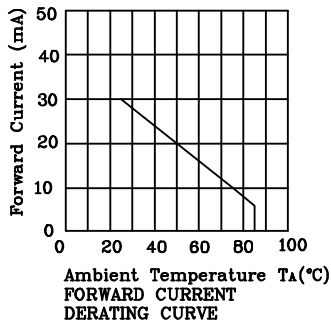
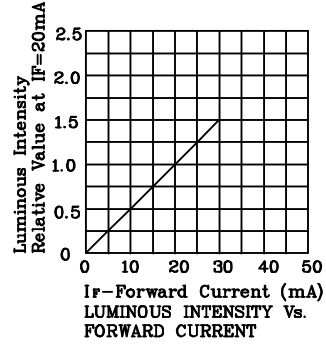
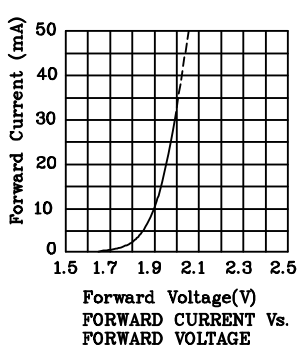
Absolute Maximum Ratings (TA=25°C)		MDK (InGaAlP)	BBA (InGaN)	Unit
Reverse Voltage	VR	5	5	V
Forward Current	IF	30	30	mA
Forward Current (Peak) 1/10Duty Cycle 0.1ms Pulse Width	iFS	185	100	mA
Power Dissipation	PT	75	120	mW
Electrostatic Discharge Threshold (HBM)		-	1000	V
Operating Temperature	TA	-40 ~ +85		°C
Storage Temperature	Tstg	-40 ~ +85		

Operating Characteristics (TA=25°C)		MDK (InGaAlP)	BBA (InGaN)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	1.95	3.2	V
Forward Voltage (Max.) (IF=20mA)	VF	2.5	4.0	V
Reverse Current (Max.) (VR=5V)	IR	10	10	uA
Wavelength Of Peak Emission (Typ.) (IF=20mA)	λP	650	468	nm
Wavelength Of Dominant Emission (Typ.) (IF=20mA)	λD	635	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	$\Delta\lambda$	28	21	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	35	100	pF

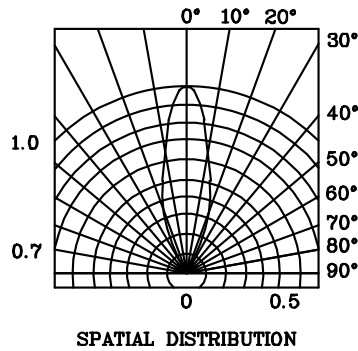
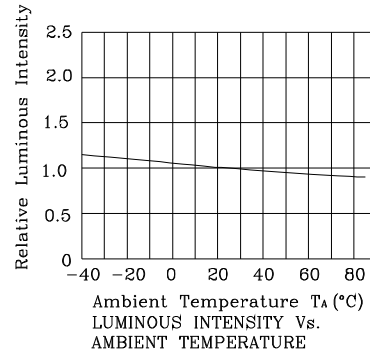
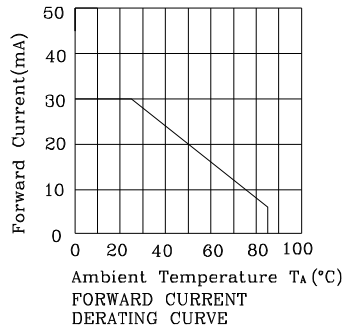
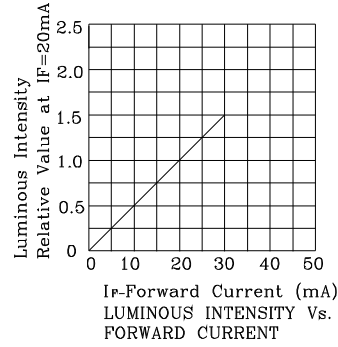
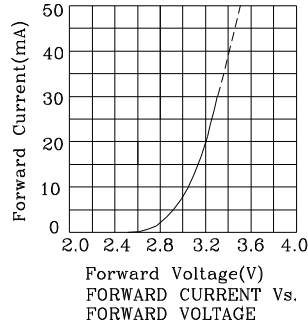
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λP	Viewing Angle 2 θ 1/2
				min.	typ.		
ZMDKBBA55W-8	Red	InGaAlP	Water Clear	110	497	650	30°
	Blue	InGaN		70	218	468	



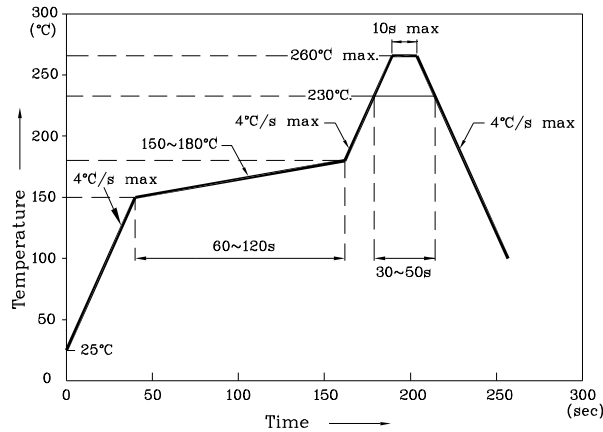
❖ MDK



❖ **BBA**



Reflow Soldering Profile For Lead-free SMT Process.

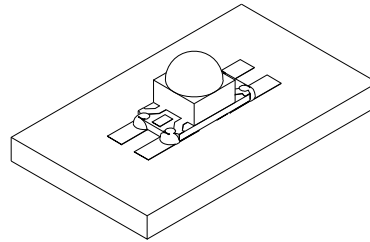
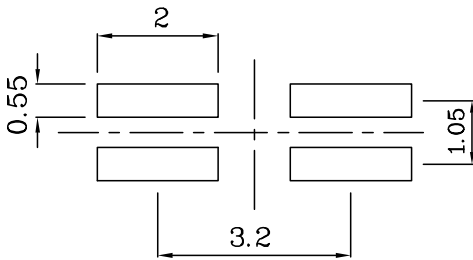


Notes:

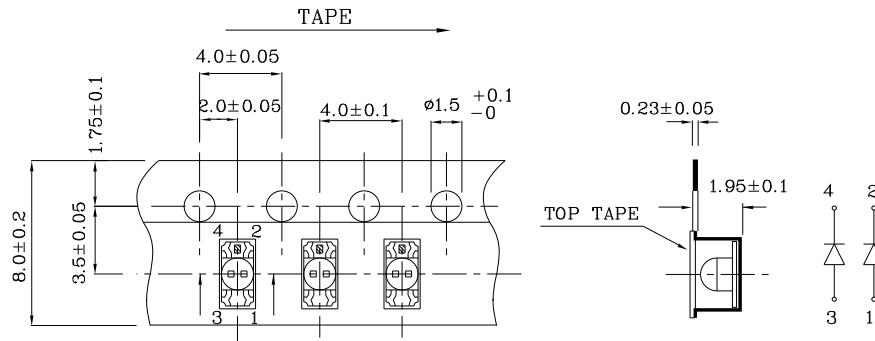
1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern
(Units : mm;Tolerance:± 0.1)

❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

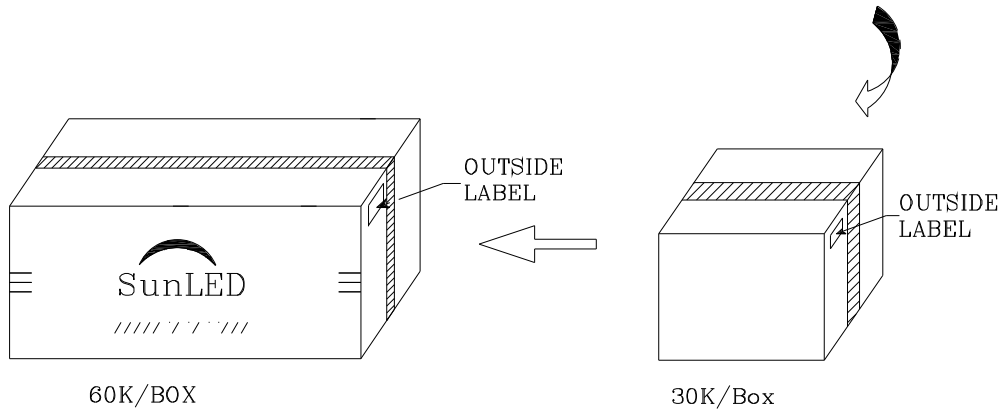
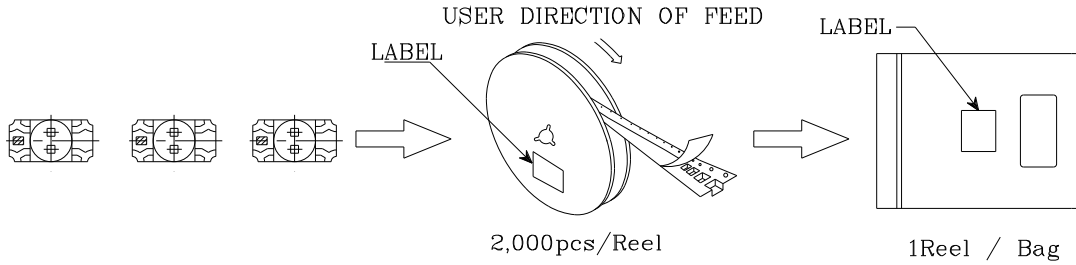

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

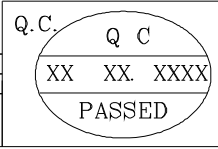

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

ZMDKBBA55W-8

	
P/NO : Zxx55x-8	
QTY : 2,000 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	